

SUBSTITUTE SPECIFICATION

ABSTRACT OF DISCLOSURE

A method and apparatus for cooling an electronic component, such as an optoelectronic device, is described. The method involves arranging a porous material to be able to receive heat from the electronic component and removing
5 heat from the porous material as a result of vaporization of a coolant delivered to the porous material. In this manner, a temperature gradient is generated that causes heat to flow from the electronic device to the porous material, resulting in the electronic device being cooled.